



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

April 5, 2010

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231 Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006 Examiner: Bareford

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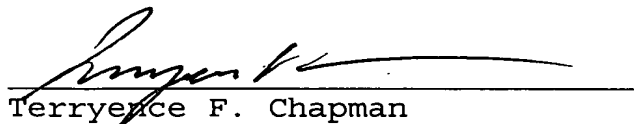
LETTER TO EXAMINER

Sir:

This Request for Continued Examination is being filed in order to have the Amendment After Final Rejection dated March 4, 2010 entered into the record of the present application. As discussed in the last Response, the instant invention provides the addition of a water-soluble nitrogen-containing polymer to an electroless copper plating solution containing phosphinic acid and glyoxylic acid as reducing agents to improve the initial plating reactivity through the catalyst metal and thereby enable the provision of uniform plating at a lower temperature on a semiconductor or other mirrored-surface substrate. This allows the plating deposition speed to be controlled, the crystals to become finer and the adhesion of the plating to a wafer or other mirrored-surface substrate to increase. It is respectfully submitted that the prior art cited by the Examiner does not

disclose the presently claimed invention. Favorable consideration is respectfully solicited.

Respectfully submitted,


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Encl: None

110.10/07